

ABSTRACT

TITLE: "SUBSTRATE-CUTTING SYSTEM, SUBSTRATE-PRODUCING APPARATUS, SUBSTRATE-SCRIBING METHOD, AND SUBSTRATE-CUTTING METHOD"

A clamping device (50) is installed on a stand (10) with a hollow rectangular parallelepiped shape such that at least one place at a side edge portion of a mother board transported in the stand (10) is clamped. A pair of substrate-cutting devices for cutting the mother substrate, clamped by the clamping device (50), from its upper face and lower face is provided on a scribing device guide body (30). The scribing device guide body (30) is reciprocally movable along one side of the hollow rectangular parallelepiped. The pair of substrate-cutting devices is installed so as to be movable along the direction perpendicular to the movement direction of the scribing device guide body (30). The mother substrate clamped by the clamping device is supported by a substrate-supporting device (20), as shown in Figure 3.